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Sheet 1 of 1

FORM PTO-1449 INFORMATION DISCLOSURE STATEMENT				ATTY DOCKET NO. 51833		SERIAL NO. 10/816,627	
				APPLICANT(S): Beica et al.			
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UNITED STATES PATENT DOCUMENTS							
EXAM. INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FIL. DATE IF APPR
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CK	AB	5,646,068	07/08/1997	Wilson et al.			
CK	AC	5,854,514	12/29/1998	Roldan et al.			
CK	AD	5,990,564	11/23/1999	Degani et al.			
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CK	BA	1 001 054	05/17/2000	Europe			
CK	BB	0 854 206	08/16/2001	Europe			
CK	BC	9-143786	06/03/1997	Japan			
CK	BD	WO 01/02627	01/11/2001	International			
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CK	CA	Karim et al.; "Lead-Free Solder Bump Technologies for Flip-Chip Packaging Applications"; 2001 International Symposium on Microelectronics; pp. 581-583.					
CK	CB	Patent Abstracts of Japan, Vol. 2000, No. 23; 10 February 2001 & JP 2001 164396 A (Ishihara Chem. Co. Ltd.; Daiwa Kasei Kenkyusho: KK).					
Examiner: <i>Christy Karsick</i>				Date: 1/6/06			

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